SHENZHEN TIBTRONIX TECHNOLOGY CO., LTD.



TXBLXG60-23/32

10Gb/s 60km BiDi XFP Transceiver Hot Pluggable, Single LC, 1270/1330nm, CWDM DFB&APD, Single mode

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Shenzhen Tibtronix Technology Co., Ltd.

3/F,12th Building, Nangang 1st Industrial Park, Baimang Xili, Songbai Road, Nanshan District, Shenzhen, China

Tel: +86 755 23316583 Fax: +86 755 29810056 E-mail: sales@tibtronix.com http://www.tibtronix.com

Features:

- ♦ Supports 9.95Gb/s to 11.3Gb/s bit rates
- ♦ Hot-pluggable XFP footprint
- ♦ Single LC for Bi-directional Transmission
- ♦ Maximum link length of 60km
- ♦ Built-in 1270/1330 WDM
- ♦ Uncooled 1270nm or 1330nm CWDM DFB Laser
- ♦ APD Receiver
- ♦ Power dissipation <2W</p>
- ♦ No Reference Clock required
- ♦ Built-in digital diagnostic functions
- ♦ Temperature range 0°C to 70°C
- ♦ Very low EMI and excellent ESD protection
- ♦ RoHS Compliant Part

Applications:

- ♦ 10GBASE-LR/LW Ethernet
- ♦ SONET OC-192 /SDH
- ♦ 1200-SM-LL-L 10G Fibre Channel

Description:

TIBTRONIX' TXBLXG60D-23/32 Bi-directional 10Gb/s (XFP) transceivers are compliant with the current XFP Multi-Source Agreement (MSA) Specification. They comply with 10-Gigabit Ethernet 10GBASE-LR/LW per IEEE 802.3ae and 10G Fibre Channel 1200-SM-LL-L. Digital diagnostics functions are available via a 2-wire serial interface, as specified in the XFP MSA.



Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Storage Temperature	T _{ST}	-40	+85	$^{\circ}$
Case Operating Temperature	T _{IP}	0	+70	\mathbb{C}
Supply Voltage	V _{CC3}	-0.5	+4.0	V

● Electrical Characteristics (T_{OP} = 0 to 70 °C)

Parameter	Symbol	Min	Тур	Max	Unit	Note	
Supply Voltage	Vcc3	3.13		3.45	V		
Supply Current	Icc3			500	mA		
Module total power	Р			2	W		
Transmitter							
Input differential impedance	Rin		100		Ω	1	
Differential data input swing	Vin,pp	150		820	mV		
Transmit Disable Voltage	V_D	2.0		Vcc	٧		
Transmit Enable Voltage	V _{EN}	GND		GND+ 0.8	V		
Transmit Disable Assert Time	T_off			100	ms		
Tx Enable Assert Time	T_on			100	ms		
Receiver							
Differential data output swing	Vout,pp	300	500	850	mV		
Data output rise time	tr			35	ps	2	
Data output fall time	tf			35	ps	2	
LOS Fault	V _{LOS} fault	Vcc – 0.5		Vcc _{HOST}	V	3	
LOS Normal	V _{LOS norm}	GND		GND+0.5	V	3	
Power Supply Rejection	PSR	See Note 4 below				4	

Notes

- 1. After internal AC coupling.
- 2. 20 80 %
- 3.Loss of Signal is open collector to be pulled up with a 4.7k 10kohm resistor to 3.15 3.6V. Logic 0 indicates normal operation; logic 1 indicates no signal detected.
- 4. Per Section 2.7.1. in the XFP MSA Specification.



Optical Parameters(T_{OP} = 0 to 70°C)

Parar	Symbol	Min	Тур	Max	Unit	Ref.	
Transmitter							
Operating Date Rate		BR	9.95		11.3	Gb/s	
Bit Error Rate		BER			10 ⁻¹²		
Maximum Launch P	ower	P _{MAX}	0		+5	dBm	1
Optical Center	FTP960-2733	λ	1260	1270	1280	nm	
Wavelength	FTP960-3327	^	1320	1330	1340	nm	
Optical Extinction R	atio	ER	3.5			dB	
Spectral Width		Δλ			1	nm	
Sidemode Supression	on ratio	SSRmin	30			dB	
Rise/Fall Time (20%	~80%)	Tr/Tf			50	ps	
Average Launch pov	Average Launch power of OFF				-30	dBm	
Transmitter							
Tx Jitter		Txj	Compliant with each standard				
			requirements				
Optical Eye Mask			IEEE802.3ae				2
Receiver							
Operating Date Rate	Operating Date Rate		9.95		11.3	Gb/s	
Receiver Sensitivity		Sen			-22	dBm	2
Maximum Input Power		P _{MAX}	-7			dBm	2
Optical Center	FTP960-2733	1	1320	1330	1340	n.m.	
Wavelength	FTP960-3327	λς	1260	1270	1280	nm	
Receiver Reflectance		Rrx			-27	dB	
LOS De-Assert		LOS _D			-23	dBm	
LOS Assert	LOS Assert		-33			dBm	
LOS Hysteresis	LOS Hysteresis		0.5		5	dB	

Notes:

- 1. The optical power is launched into SMF.
- 2. Measured with a PRBS 2^{31} -1 test pattern @10.3125Gbps BER<10⁻¹².



Pin Assignment

Diagram of Host Board Connector Block Pin Numbers and Name

GND 1 2 VEE5 Mod_Desel 3 Interrupt 5 TX_DIS VCC5 6 7 GND VCC3 8 VCC3 9 SCL 10 11 SDA Mod_ABS 12 13 Mod_Nr RX_LOS 14 GND

GND 30 29 TD+ TD-28 GND 27 GND 26 RefCLK-25 24 RefCLK+ GND 23 VCC2 22 P_Down/RST 21 Vcc2 20 GND 19 RD+ 18 RD-17 GND

Bottom of Board (As view through top of board)

Top of Board

Pin Function Definitions

Pin	Logic	Symbol	Name/Description	
1		GND	Module Ground	1
2		VEE5	Optional –5.2 Power Supply – Not required	
3	LVTTL-I	Mod-Desel	Module De-select; When held low allows the module to	
			respond to 2-wire serial interface commands	
4	LVTTL-O	Interrupt	Interrupt (bar); Indicates presence of an important	2
			condition which can be read over the serial 2-wire	
			interface	
5	LVTTL-I	TX_DIS	Transmitter Disable; Transmitter laser source turned off	
6		VCC5	+5 Power Supply	
7		GND	Module Ground	1



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8		VCC3	+3.3V Power Supply	
9		VCC3	+3.3V Power Supply	
10	LVTTL-I	SCL	Serial 2-wire interface clock	2
11	LVTTL-	SDA	Serial 2-wire interface data line	2
	1/0	3571	Serial 2 Wife interrace data infe	_
12	LVTTL-O	Mod Abs	Module Absent; Indicates module is not present.	2
		_	Grounded in the module.	
13	LVTTL-O	Mod_NR	Module Not Ready;	2
14	LVTTL-O	RX_LOS	Receiver Loss of Signal indicator	2
15		GND	Module Ground	1
16		GND	Module Ground	1
17	CML-O	RD-	Receiver inverted data output	
18	CML-O	RD+	Receiver non-inverted data output	
19		GND	Module Ground	1
20		VCC2	+1.8V Power Supply – Not required	
21	LVTTL-I	P_Down/RS	Power Down; When high, places the module in the low	
		T	power stand-by mode and on the falling edge of	
			P_Down initiates a module reset	
			Reset; The falling edge initiates a complete reset of the	
			module including the 2-wire serial interface, equivalent	
			to a power cycle.	
22		VCC2	+1.8V Power Supply – Not required	
23		GND	Module Ground	1
24	PECL-I	RefCLK+	Reference Clock non-inverted input, AC coupled on the	3
			host board – Not required	_
25	PECL-I	RefCLK-	Reference Clock inverted input, AC coupled on the host	3
26		CND	board – Not required	4
26		GND	Module Ground	1
27	01	GND	Module Ground	1
28	CML-I	TD-	Transmitter inverted data input	
29	CML-I	TD+	Transmitter non-inverted data input	
30		GND	Module Ground	1

Note

- 1. Module circuit ground is isolated from module chassis ground within the module.
- 2. Open collector; should be pulled up with 4.7k 10k ohms on host board to a voltage between 3.15Vand 3.45V.
- 3. A Reference Clock input is not required.

Digital Diagnostic Functions

As defined by the XFP MSA 1, TIBTRONIX's XFP transceivers provide digital diagnostic functions via a 2-wire serial interface, which allows real-time access to the following operating parameters:

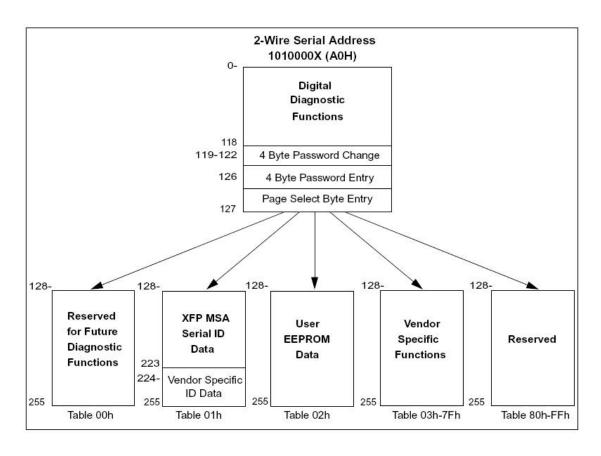


- ✓ Transceiver temperature
- ✓ Laser bias current
- ✓ Transmitted optical power
- ✓ Received optical power
- ✓ Transceiver supply voltage

It also provides a sophisticated system of alarm and warning flags, which may be used to alert end-users when particular operating parameters are outside of a factory-set normal range.

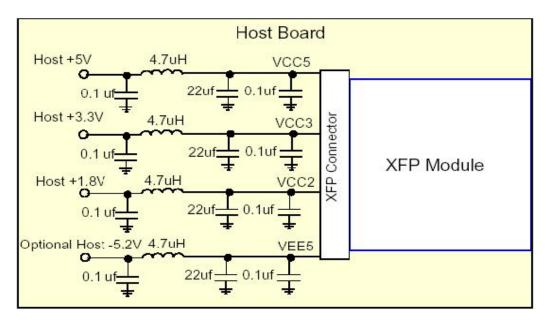
The operating and diagnostics information is monitored and reported by a Digital Diagnostics Transceiver Controller (DDTC) inside the transceiver, which is accessed through the 2-wire serial interface. When the serial protocol is activated, the serial clock signal (SCL pin) is generated by the host. The positive edge clocks data into the XFP transceiver into those segments of its memory map that are not write-protected. The negative edge clocks data from the XFP transceiver. The serial data signal (SDA pin) is bi-directional for serial data transfer. The host uses SDA in conjunction with SCL to mark the start and end of serial protocol activation. The memories are organized as a series of 8-bit data words that can be addressed individually or sequentially. The 2-wire serial interface provides sequential or random access to the 8 bit parameters, addressed from 000h to the maximum address of the memory.

For more detailed information including memory map definitions, please see the XFP MSA Specification.

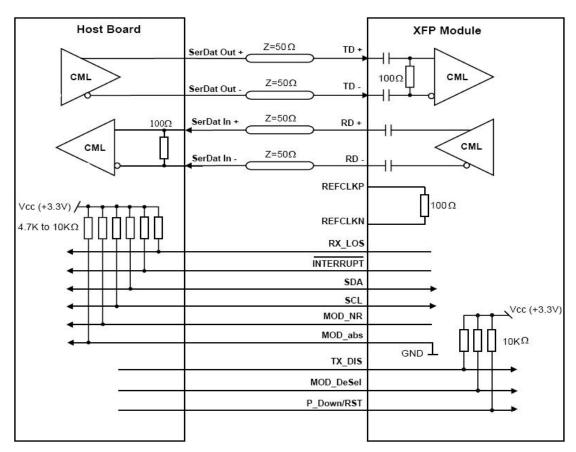




Recommended Circuit



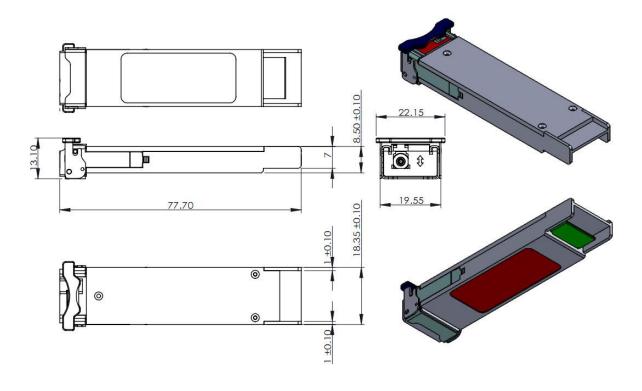
Recommended Host Board Power Supply Circuit



Recommended High-speed Interface Circuit



Mechanical Dimensions



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